

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD50P04P4L-11	**Issued**	14. May 2021
MA#	MA002959966		
Package	PG-TO252-3-313	**Weight***	318.30 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.613	0.51	0.51	5068	5068
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		463	
	non noble metal	copper	7440-50-8	147.096	46.21	46.27	462132	462734
wire	non noble metal	aluminium	7429-90-5	2.939	0.92	0.92	9233	9233
encapsulation	inorganic material	zincoxide	1314-13-2	1.404	0.44		4412	
	miscellaneous	miscellaneous	-	7.021	2.21		22058	
	plastics	epoxy resin	-	21.064	6.62		66175	
	inorganic material	silicondioxide	60676-86-0	110.935	34.85	44.12	348523	441168
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11750	11750
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4463	4474
solder	non noble metal	tin	7440-31-5	0.033	0.01		105	
	noble metal	silver	7440-22-4	0.042	0.01		131	
	non noble metal	lead	7439-92-1	1.594	0.50	0.52	5009	5245
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.02	6.03	60250	60328
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com